

RELIABILITY REPORT
FOR
MAX4675EUT+T
PLASTIC ENCAPSULATED DEVICES

September 29, 2014

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX4675EUT+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX4675/MAX4676 single analog switches feature 3 (max) on-resistance (RON) and 0.7 flatness when operating from dual $\pm 5V$ supplies. These switches can handle Rail-to-Rail analog signals. Off-leakage current is 0.1nA at TA = +25°C. The MAX4675/MAX4676 are ideal in low-distortion applications and are the preferred solution over mechanical relays in automated test equipment or applications where current switching is required. They are more reliable than mechanical relays, have low power requirements ($<1\mu A$), and are available in a space-saving 6-pin SOT23 package. The MAX4675 has a single normally open (NO) switch, and the MAX4676 has a single normally closed (NC) switch. The MAX4675/MAX4676 operate from either a single +2.7V to +5.5V or dual $\pm 2.7V$ to $\pm 5.5V$ supplies, making them ideal for use in digital card applications and single-ended 75 systems.

II. Manufacturing Information

A. Description/Function:	3 Single SPST Analog Switches
B. Process:	B3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	July 22, 2000

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0185
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	74.6°C/W
M. Multi Layer Theta Jc:	6.1°C/W

IV. Die Information

A. Dimensions:	42X61 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- | | |
|-----------------------------------|---|
| A. Quality Assurance Contacts: | Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA) |
| B. Outgoing Inspection Level: | 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects. |
| C. Observed Outgoing Defect Rate: | < 50 ppm |
| D. Sampling Plan: | Mil-Std-105D |

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 152 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 7.23 \times 10^{-9}$$

$$\lambda = 7.23 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.25 @ 25C and 4.22 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot N25ACA005A, D/C 0414)

The AH36 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX4675EUT+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	79	0	N25ACA005A, D/C 0414
	Biased	& functionality	73	0	I25AAU004A, D/C 0028
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots